

| | | | |
|---|---|--|------------------|
| PCN Number: | 20221004001.1 | PCN Date: | October 07, 2022 |
| Title: | Qualification of new Fab site (RFAB) using qualified Process Technology, Die Revision, and additional Assembly Sites & BOM options for select devices | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services |
| Proposed 1st Ship Date: | Jan 5, 2023 | Sample requests accepted until: | Nov 7, 2022* |

***Sample requests received after Nov 7, 2022 will not be supported.**

Change Type:

| | | | | | |
|-------------------------------------|-----------------|-------------------------------------|---------------------------|-------------------------------------|--------------------------|
| <input checked="" type="checkbox"/> | Assembly Site | <input checked="" type="checkbox"/> | Assembly Process | <input checked="" type="checkbox"/> | Assembly Materials |
| <input checked="" type="checkbox"/> | Design | <input checked="" type="checkbox"/> | Electrical Specification | <input type="checkbox"/> | Mechanical Specification |
| <input type="checkbox"/> | Test Site | <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process |
| <input type="checkbox"/> | Wafer Bump Site | <input type="checkbox"/> | Wafer Bump Material | <input type="checkbox"/> | Wafer Bump Process |
| <input checked="" type="checkbox"/> | Wafer Fab Site | <input checked="" type="checkbox"/> | Wafer Fab Materials | <input checked="" type="checkbox"/> | Wafer Fab Process |
| | | <input type="checkbox"/> | Part number change | | |

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a new fab & process technology (RFAB, LBC9) and Assembly site & BOM option for selected devices as listed below in the product affected section. Construction differences are noted below:

| Current Fab Site | | | Additional Fab Site | | |
|------------------|-----------|----------------|---------------------|---------|----------------|
| Current Fab Site | Process | Wafer Diameter | Additional Fab Site | Process | Wafer Diameter |
| FR-BIP-1 | ASLNONC10 | 200 mm | RFAB | LBC9 | 300 mm |

The die was also changed as a result of the process change.

Group 1 Devices Table (DCU):

| | HNA | HFTF |
|---------------------------------|-------------|------------------------|
| Mount Compound | SID#400180 | SID#A-18 |
| Bond wire composition, diameter | Au, 0.8 mil | Cu, 0.8 mil or 1.0 mil |
| Mold Compound | SID#450207 | SID#R-31 or SID#R-32 |
| Lead finish | NiPdAu | Matte Sn or NiPdAu |

Group 2 Device Table (DCT):

| | HNA | HIT | HFTF |
|---------------------------------|-------------|-------------|-------------|
| Mount Compound | SID#400728 | SID#RZ241C | SID#A-18 |
| Bond wire composition, diameter | Au, 1.0 mil | Au, 0.8 mil | Cu, 0.8 mil |
| Mold Compound | SID#450420 | SID#G600K | SID#R-30 |
| Lead finish | NiPdAu | NiPdAu | Matte Sn |

Upon expiry of this PCN TI will combine lead free solutions in a single **standard part number**. For example; [SN74LVC2T45DCUR](#) – can ship with both Matte Sn and NiPdAu/Ag.

Example:

- Customer order for 7500 units of SN74LVC2T45DCUR with 2500 units SPQ (Standard Pack Quantity per Reel).
- TI can satisfy the above order in one of the following ways.
 - I. 3 Reels of NiPdAu finish.
 - II. 3 Reels of Matte Sn finish
 - III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish.
 - IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish.

The datasheets will be changing as a result of the above mentioned changes. The datasheet

change details can be reviewed in the datasheet revision history shown below. The links to the revised datasheets are available in the table below.

| Changes from Revision K (June 2017) to Revision L (October 2022) | Page |
|--|-------------|
| • Updated the numbering format for tables, figures, and cross-references throughout the document..... | 1 |
| • Updated the thermals in the <i>Thermal Information</i> section..... | 5 |
| • Extended the minimum specifications for lower delays in the <i>Switching Characteristics</i> sections..... | 8 |

| Product Folder | Current Datasheet Number | New Datasheet Number | Link to full datasheet |
|----------------|--------------------------|----------------------|--------------------------------|
| SN74LVC2T45 | SCES516K | SCES516L | Datasheet Link |

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

| RoHS | REACH | Green Status | IEC 62474 |
|---|---|---|---|
| <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change |

Changes to product identification resulting from this PCN:

Fab Site Information:

| Chip Site | Chip Site Origin Code (20L) | Chip Site Country Code (21L) | Chip Site City |
|-------------|-----------------------------|------------------------------|-------------------|
| FR-BIP-1 | TID | DEU | Freising |
| RFAB | RFB | USA | Richardson |

Die Rev:

| Current | New |
|--------------|--------------|
| Die Rev [2P] | Die Rev [2P] |
| - | A |

| Assembly Site | Assembly Site Origin (22L) | Assembly Country Code (23L) | Assembly City |
|---------------|----------------------------|-----------------------------|---------------------|
| HNA | HNT | THA | Ayutthaya |
| HIT | HTC | JPN | Kitatsugaru, Aomori |
| HFTFAT | HFT | CHN | Hefei |

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

| | |
|---------------------|----------|
| MSL 2 / 260C/1 YEAR | SEAL DT |
| MSL 1 / 235C/UNLIM | 03/29/04 |

OPT:
ITEM: 39
LBL: 5A (L)T0:1750





(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) ~~CSO: CHE~~ (21L) ~~CCO: USA~~
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:**Group 1 Device list:**

| | | |
|-----------------|-----------------|-------------------|
| SN74LVC2T45DCUR | SN74LVC2T45DCUT | SN74LVC2T45DCURG4 |
|-----------------|-----------------|-------------------|

Group 2 Device list:

| | |
|-----------------|-----------------|
| SN74LVC2T45DCTR | SN74LVC2T45DCTT |
|-----------------|-----------------|

TI Information
Selective Disclosure

Qualification Report
Approve Date 19-SEPTEMBER-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: SN74LVC2T45DCTT | Qual Device: SN74LVC2T45DCTR | QBS Reference: SN74LVC2T45QDCURQ1 |
|-------|----|-------------------------------|------------------------------|------------|---|---|--|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | - | 1/77/0 |
| UHAST | A3 | Autoclave | 121C/15psig | 96 Hours | - | - | 1/77/0 |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | - | - | 1/77/0 |
| HTSL | A6 | High Temperature Storage Life | 175C | 500 Hours | - | - | 1/45/0 |
| HTOL | B1 | Life Test | 125C | 1000 Hours | - | - | 1/77/0 |
| ESD | E2 | ESD CDM | - | 250 Volts | - | 1/3/0 | - |
| ESD | E2 | ESD CDM | - | 500 Volts | - | - | 1/3/0 |
| ESD | E2 | ESD HBM | - | 1000 Volts | - | 1/3/0 | - |
| ESD | E2 | ESD HBM | - | 2000 Volts | - | - | 1/3/0 |
| LU | E4 | Latch-Up | Per JESD78 | - | - | 1/3/0 | - |
| CHAR | E5 | Electrical Characterization | Per Datasheet Parameters | - | - | 1/30/0 | - |
| CHAR | E5 | Electrical Distributions | Cpk>1.67 Room, hot, and cold | - | - | - | 3/90/0 |

- QBS: Qual By Similarity
- Qual Device SN74LVC2T45DCTT is qualified at MSL1 260C
- Qual Device SN74LVC2T45DCTR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2109-076

Qualification Report
Approve Date 19-SEPTEMBER-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: SN74LVC2T45DCUR | Qual Device: SN74LVC2T45DCURG4 | Qual Device: SN74LVC2T45DCUT | QBS Reference: SN74LVC2T45QDCURQ1 |
|-------|----|-------------------------------|------------------------------|------------|---|---|---|--|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | - | - | 1/77/0 |
| UFAST | A3 | Autoclave | 121C/15psig | 96 Hours | - | - | - | 1/77/0 |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | - | - | - | 1/77/0 |
| HTSL | A6 | High Temperature Storage Life | 175C | 500 Hours | - | - | - | 1/45/0 |
| HTOL | B1 | Life Test | 125C | 1000 Hours | - | - | - | 1/77/0 |
| ESD | E2 | ESD CDM | - | 250 Volts | 1/3/0 | - | - | - |
| ESD | E2 | ESD CDM | - | 500 Volts | - | - | - | 1/3/0 |
| ESD | E2 | ESD HBM | - | 2000 Volts | - | - | - | 1/3/0 |
| CHAR | E5 | Electrical Characterization | Per Datasheet Parameters | - | 1/30/0 | - | - | - |
| CHAR | E5 | Electrical Distributions | Cpk>1.67 Room, hot, and cold | - | - | - | - | 3/90/0 |

- QBS: Qual By Similarity
- Qual Device SN74LVC2T45DCUR is qualified at MSL1 260C

- Qual Device SN74LVC2T45DCURG4 is qualified at MSL1 260C
- Qual Device SN74LVC2T45DCUT is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2109-078

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|---------------------------|--|
| WW Change Management Team | PCN_ww_admin_team@list.ti.com |

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